

JUN 21 2004

Page No.: 1 of: 1

**INFORMATION DISCLOSURE
CITATION FORM FOR
PATENT APPLICATION
(FORM PTO-1449)
(Substitute)**

Docket No.: YOR920030196US1

Serial No.: 10/700,327

Applicant(s): Paul S. ANDRY et al.

Filing Date: 11/03/03

Group:

U.S. PATENTS

Initials	Patent Number	Issue Date	Name	Class	Sub-class	Filing date
	5,244,143	09/14/93	Ference et al.			
	5,775,569	07/07/98	Berger et al.			
	5,998,292	12/07/99	Black et al.			
	6,506,332	01/14/03	Pedigo			
	6,593,644	07/15/03	Chiu et al.			

FOREIGN PATENT DOCUMENTS

Initials	Document Number	Date	Country	Name	Translation? Yes/No/n/a

OTHER DOCUMENTS (Title, Author, Date, Pages, Etc., if known)

	"Filling the via hole of IC by VPES (Vacuum Printing Encapsulation Systems for stacked chip (3D Packaging), A. Okuno et al., 2002 Electronics Components and Technology Conference

Examiner's Signature:

Date Considered:

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